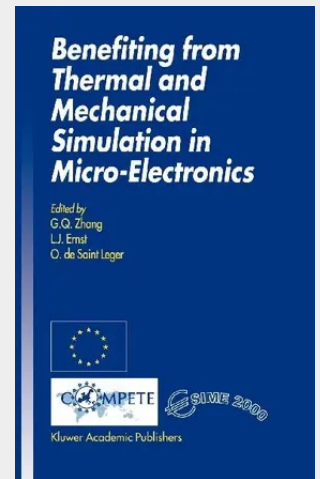


## Benefiting from Thermal and Mechanical Simulation in Micro-Electronics

Benefiting from Thermal and Mechanical Simulation in Micro-Electronics presents papers from the first international conference on this topic, EuroSimE2000. For the first time, people from the electronics industry, research institutes, software companies and universities joined together to discuss present and possible future thermal and mechanical related problems and challenges in micro-electronics; the state-of-the-art methodologies for thermal & mechanical simulation and optimization of micro-electronics; and the perspectives of future simulation and optimization methodology development. Main areas covered are:- Benefiting from Thermal and Mechanical Simulation in Micro-Electronics is suitable for students at graduate level and beyond, and for researchers, designers and specialists in the fields of microelectronics and mechanics.

Benefiting from Thermal and Mechanical Simulation in Micro-Electronics presents papers from the first international conference on this topic, EuroSimE2000. For the first time, people from the electronics industry, research institutes, software companies and universities joined together to discuss present and possible future thermal and mechanical related problems and challenges in micro-electronics; the state-of-the-art methodologies for thermal & mechanical simulation and optimization of micro-electronics; and the perspectives of future simulation and optimization methodology development. Main areas covered are:-



**106,99 €**  
99,99 € (zzgl. MwSt.)

*Lieferfrist: bis zu 10 Tage*

**Artikelnummer:** 9780792372783  
**Medium:** Buch  
**ISBN:** 978-0-7923-7278-3  
**Verlag:** Humana  
**Erscheinungstermin:** 31.12.2000  
**Sprache(n):** Englisch  
**Auflage:** 2000  
**Produktform:** Gebunden  
**Gewicht:** 1040 g  
**Seiten:** 192  
**Format (B x H):** 160 x 241 mm

